

Title (en)

CYANIDE-FREE ELECTROPLATING BATH FOR DEPOSITION OF GOLD AND GOLD ALLOYS

Title (de)

CYANIDFREIES GALVANISCHES BAD ZUR ABSCHIEDUNG VON GOLD UND GOLDLEGIERUNGEN

Title (fr)

BAIN GALVANOPLASTIQUE SANS CYANURE POUR DEPOT D'OR ET D'ALLIAGES D'OR

Publication

**EP 0907767 B1 20020213 (DE)**

Application

**EP 97933686 A 19970721**

Priority

- DE 19629658 A 19960723
- EP 9703903 W 19970721

Abstract (en)

[origin: DE19629658A1] Cyanide-free electroplating baths for deposition of gold and gold alloy coatings, using sulfurous gold complexes that are stable for a relatively long time, can be used with current densities over 1 A/dm<sup>2</sup> and are practically odor-free, are obtained when the sulfurous compounds used are mercaptosulfonic acids, disulfide sulfonic acids or salts thereof.

IPC 1-7

**C25D 3/48**; **C25D 3/62**

IPC 8 full level

**C25D 3/48** (2006.01); **C25D 3/62** (2006.01)

CPC (source: EP KR US)

**C25D 3/48** (2013.01 - EP KR US); **C25D 3/62** (2013.01 - EP KR US)

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